



Low Voltage/Low Skew, 1:8 PCI/PCI-X Zero Delay Clock Generator

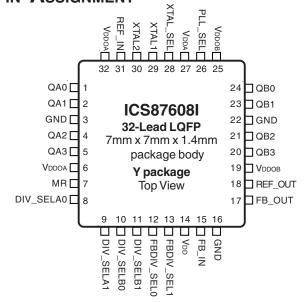
GENERAL DESCRIPTION

The ICS87608I has a selectable REF_CLK or crystal input. The REF_CLK input accepts LVCMOS or LVTTL input levels. The ICS87608I has a fully integrated PLL along with frequency configurable clock and feedback outputs for multiplying and regenerating clocks with "zero delay".

The ICS87608I is a 1:8 PCI/PCI-X Clock Generator. The ICS87608I has a selectable REF_CLK or crystal input. The REF_CLK input accepts LVCMOS or LVTTL input levels. The ICS87608I has a fully integrated PLL along with frequency configurable clock and feedback outputs for multiplying and regenerating clocks with "zero delay". The PLL's VCO has an operating range of 250MHz-500MHz, allowing this device to be used in a variety of general purpose clocking applications. For PCI/PCI-X applications in particular, the VCO frequency should be set to 400MHz. This can be accomplished by supplying 33.33MHz, 25MHz, 20MHz, or 16.66MHz on the reference clock or crystal input and by selecting ÷12, ÷16, ÷20, or ÷24, respectively as the feedback divide value. The dividers on each of the two output banks can then be independently configured to generate 33.33MHz $(\div 12)$, 66.66MHz $(\div 6)$, 100MHz $(\div 4)$, or 133.33MHz $(\div 3)$.

The ICS87608I is characterized to operate with its core supply at 3.3V and each bank supply at 3.3V or 2.5V. The ICS87608I is packaged in a small 7x7mm body LQFP, making it ideal for use in space-constrained applications.

PIN ASSIGNMENT



FEATURES

- Fully integrated PLL
- Eight LVCMOS/LVTTL outputs, 15Ω typical output impedance
- Selectable crystal oscillator interface or LVCMOS/LVTTL REF_IN clock input
- Maximum output frequency: 166.67MHz
- Maximum crystal input frequency: 38MHz
- Maximum REF_IN input frequency: 41.67MHz
- Individual banks with selectable output dividers for generating 33.333MHz, 66.66MHz, 100MHz and 133.333MHz
- Separate feedback control for generating PCI / PCI-X frequencies from a 16.66MHz or 20MHz crystal, or 25MHz or 33.33MHz reference frequency
- VCO range: 200MHz to 500MHz
- Cycle-to-cycle jitter: 120ps (maximum), @ 3.3V
- Period jitter, RMS: 20ps (maximum)
- Output skew: 250ps (maximum)
- Bank skew: 60ps (maximum)
- Static phase offset: 160ps ± 160ps
- Voltage Supply Modes:

 $V_{\scriptscriptstyle DD}$ (core/inputs), $V_{\scriptscriptstyle DDA}$ (analog supply for PLL),

V_{DDOA} (output bank A),

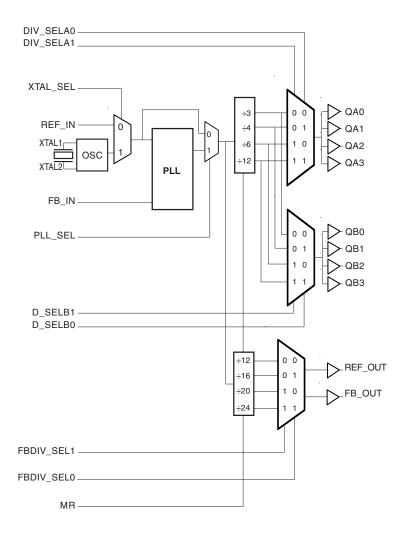
V_{DDOB} (output bank B, REF_OUT, FB_OUT)

V_{DD}/V_{DDA}/V_{DDOA}/V_{DDOB} 3.3/3.3/3.3/3.3 3.3/3.3/2.5/3.3 3.3/3.3/3.3/2.5 3.3/3.3/2.5/2.5

- -40°C to 85°C ambient operating temperature
- Available in both standard and lead-free RoHS compliant packages



BLOCK DIAGRAM



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TABLE 1. PIN DESCRIPTIONS

8, DIV_SELA0, DIV_SELA1, DIV_SELB0, DIV_SELB1 12, FBDIV_SEL0, FBDIV_SEL1 14 VDD Power Pulldown Selects divide value for clock outputs as described in Table 3. LVCMOS / LVTTL interface levels. Selects divide value for reference clock output and feedback output. LVCMOS / LVTTL interface levels. Core supply pin.	Number	Name	Т	уре	Description
3, 16, 22 GND Power Power Supply ground. 6, 32 V _{DDOA} Power Output supply pins for Bank A outputs. 7 MR Input Pulldown Power Selects divide value for clock outputs as described in Table 3. LVCMOS / LVTTL interface levels. 8, DIV_SELA0, 9, DIV_SELA1, 10, DIV_SELB1 DIV_SELB1 12, FBDIV_SEL0, 13 FBDIV_SEL1 Input Pulldown Pulldown Pulldown Pulldown Pulldown Pulldown Elects divide value for reference clock output and feedback output. LVCMOS / LVTTL interface levels. 14 V _{DD} Power Core supply pin. Espectback input to phase detector for generating clocks with			Output		
6, 32 V_DDOA Power Output supply pins for Bank A outputs. Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS / LVTTL interface levels. B, DIV_SELAO, 9, DIV_SELA1, DIV_SELB0, 11 DIV_SELB1 12, FBDIV_SEL0, FBDIV_SEL0, 13 FBDIV_SEL1 Pulldown Pulldown Selects divide value for reference clock output and feedback output. LVCMOS / LVTTL interface levels. 14 V_DD Power Output supply pins for Bank A outputs. Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS / LVTTL interface levels. Selects divide value for reference clock output and feedback output. LVCMOS / LVTTL interface levels. Core supply pin.	4, 5	QA2, QA3	Output		LVCMOS / LVTTL interface levels.
7 MR Input Pulldown Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS / LVTTL interface level dividers and the outputs are enabled. LVCMOS / LVTTL interface level LVCMOS / LVTTL interface levels. 10 DIV_SELB1 Input DIV_SELB1 12, FBDIV_SEL0, FBDIV_SEL0, FBDIV_SEL1 Input Pulldown LVCMOS / LVTTL interface levels. 14 V _{DD} Power Core supply pin. Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. The internal dividers are reset causing the outputs go low. The internal dividers are reset causing the outputs go low. The internal dividers are reset causing the outputs go low. The internal dividers are reset causing the outputs go low. The	3, 16, 22	GND	Power		Power supply ground.
7 MR Input Pulldown Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS / LVTTL interface level dividers and the outputs are enabled. LVCMOS / LVTTL interface level LVCMOS / LVTTL interface levels. 10 DIV_SELB1 Input DIV_SELB1 12, FBDIV_SEL0, FBDIV_SEL0, FBDIV_SEL1 Input Pulldown LVCMOS / LVTTL interface levels. 14 V _{DD} Power Core supply pin. Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic HIGH, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. When logic LOW, the internal dividers are reset causing the outputs go low. The internal dividers are reset causing the outputs go low. The internal dividers are reset causing the outputs go low. The internal dividers are reset causing the outputs go low. The internal dividers are reset causing the outputs go low. The	6, 32	V_{DDOA}	Power		Output supply pins for Bank A outputs.
9, DIV_SELA1, DIV_SELB0, DIV_SELB1 12, FBDIV_SEL1 Input FBDIV_SEL1 14 VDD Power Pulldown Selects divide value for clock outputs as described in Table 3. LVCMOS / LVTTL interface levels. Selects divide value for reference clock output and feedback output. LVCMOS / LVTTL interface levels. Core supply pin.	7		Input	Pulldown	
10, DIV_SELB0, DIV_SELB1 12, FBDIV_SEL0, FBDIV_SEL1 13 FBDIV_SEL1 14 V _{DD} Power Pulldown LVCMOS / LVTTL interface levels. LVCMOS / LVTTL interface levels. Selects divide value for reference clock output and feedback output. LVCMOS / LVTTL interface levels. Core supply pin.		DIV_SELA0,			
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12, FBDIV_SEL0, FBDIV_SEL1 Input Pulldown Selects divide value for reference clock output and feedback output. LVCMOS / LVTTL interface levels. 14 V _{DD} Power Core supply pin. Feedback input to phase detector for generating clocks with			Impat	1 dildowii	LVCMOS / LVTTL interface levels.
13 FBDIV_SEL1 Input Pulldown LVCMOS / LVTTL interface levels. 14 V _{DD} Power Core supply pin. Feedback input to phase detector for generating clocks with					
13 FBDIV_SELT : LVCMOS / LVTTL Interface levels. 14 V _{DD} Power Core supply pin. Feedback input to phase detector for generating clocks with			Input	Pulldown	
Feedback input to phase detector for generating clocks with			·		
FROM	14	V _{DD}	Power		
15 FB_IN Input Pulldown zero delay". LVCMOS / LVTTL interface levels.	15	FB_IN	Input	Pulldown	
17 FB_OUT Output Feedback output. Connect to FB_IN. LVCMOS / LVTTL interface leve	17	FB_OUT	Output		Feedback output. Connect to FB_IN. LVCMOS / LVTTL interface levels.
18 REF_OUT Output Reference clock output. LVCMOS / LVTTL interface levels.	18	REF_OUT	Output		Reference clock output. LVCMOS / LVTTL interface levels.
19, 25 V _{DDOB} Power Output supply pins for Bank B and REF_OUT, FB_OUT outputs.	19, 25	$V_{\tiny DDOB}$	Power		Output supply pins for Bank B and REF_OUT, FB_OUT outputs.
20, 21, QB3, QB2, QB1, QB0 Output Bank B clock outputs. 15Ω typical output impedance. LVCMOS / LVTTL interface levels.	1 ' ' 1	QB3, QB2,	Output		
26 PLL_SEL Input Pullup Selects between PLL and bypass mode. When HIGH, selects PLL. When LOW, selects reference clock. LVCMOS / LVTTL interface leve	26	PLL_SEL	Input	Pullup	Selects between PLL and bypass mode. When HIGH, selects PLL. When LOW, selects reference clock. LVCMOS / LVTTL interface levels.
27 V _{DDA} Power Analog supply pin. See Applications Note for filtering.	27	V _{DDA}	Power		Analog supply pin. See Applications Note for filtering.
Selects between crystal oscillator or reference clock as the PLL reference source. Selects XTAL inputs when HIGH. Selects REF_IN when LOW. LVCMOS / LVTTL interface levels.	28		Input	Pullup	reference source. Selects XTAL inputs when HIGH. Selects REF_IN
29, 30 XTAL1, XTAL2 Input Crystal oscillator interface. XTAL1 is the input. XTAL2 is the output.	29, 30		Input		Crystal oscillator interface. XTAL1 is the input. XTAL2 is the output.
31 REF_IN Input Pulldown Reference clock input. LVCMOS / LVTTL interface levels.	31	REF_IN	Input	Pulldown	Reference clock input. LVCMOS / LVTTL interface levels.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
R _{PULLUP}	Input Pullup Resistor			51		kΩ
R _{PULLDOWN}	Input Pulldown Resistor			51		kΩ
C _{PD}	Power Dissipation Capacitance	V_{DD} , V_{DDA} , $V_{DDOX} = 3.465V$			9	pF
PD	(per output); NOTE 1	$V_{DD}, V_{DDA} = 3.465V; V_{DDOX} = 2.625V$			11	pF
R _{out}	Output Impedance			15		Ω

 V_{DDOX} denotes V_{DDOA} and V_{DDOB} .



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TABLE 3A. OUTPUT CONTROL PIN FUNCTION TABLE

Inputs		Outputs						
MR	QA0:QA3	QB0:QB3, FB_OUT, REF_OUT						
1	LOW	LOW						
0	Active	Active						

TABLE 3B. OPERATING MODE FUNCTION TABLE

Inputs	Operating Meda			
PLL_SEL	Operating Mode			
0	Bypass			
1	PLL			

TABLE 3C. PLL INPUT FUNCTION TABLE

Inputs				
XTAL_SEL	PLL Input			
0	REF_IN			
1	XTAL Oscillator			

TABLE 3D. CONTROL FUNCTION TABLE

			lnnu	t o			Outputs				
			Inpu	เร			PLL_SEL =1 Frequency				
FBDIV_ SEL1	FBDIV_ SEL0	Bank B DIV_ SELB1	Bank B DIV_ SELB0	Bank A DIV_ SELA1	Bank A DIV_ SELA0	Reference Frequency Range (MHz)	QX0:QX3	QX0:QX3 (MHz)	FB_OUT (MHz)		
0	0	0	0	0	0	16.67 - 41.67	x 4	66.68 - 166.68	16.67 - 41.67		
0	0	0	1	0	1	16.67 - 41.67	x 3	50 - 125	16.67 - 41.67		
0	0	1	0	1	0	16.67 - 41.67	x 2	33.34 - 83.34	16.67 - 41.67		
0	0	1	1	1	1	16.67 - 41.67	x 1	16.67 - 41.67	16.67 - 41.67		
0	1	0	0	0	0	12.5 - 31.25	x 5.33	66.63 - 166.56	12.5 - 31.25		
0	1	0	1	0	1	12.5 - 31.25	x 4	50 - 125	12.5 - 31.25		
0	1	1	0	1	0	12.5 - 31.25	x 2.667	33.34 - 83.34	12.5 - 31.25		
0	1	1	1	1	1	12.5 - 31.25	x 1.33	16.63 - 41.56	12.5 - 31.25		
1	0	0	0	0	0	10 - 25	x 6.667	66.67 - 166.68	10 - 25		
1	0	0	1	0	1	10 - 25	x 5	50 - 125	10 - 25		
1	0	1	0	1	0	10 - 25	x 3.33	33.30 - 83.25	10 - 25		
1	0	1	1	1	1	10 - 25	x 1.66	16.60 - 41.50	10 - 25		
1	1	0	0	0	0	8.33 - 20.83	x 8	66.64 - 166.64	8.33 - 20.83		
1	1	0	1	0	1	8.33 - 20.83	x 6	50 - 125	8.33 - 20.83		
1	1	1	0	1	0	8.33 - 20.83	x 4	33.32 - 83.32	8.33 - 20.83		
1	1	1	1	1	1	8.33 - 20.83	x 2	16.66 - 41.66	8.33 - 20.83		

NOTE: VCO frequency range for all configurations above is 200MHz to 500MHz.



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ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{DD} 4.6V

Inputs, $V_{DD} + 0.5 \text{ V}$

Outputs, V_{O} -0.5V to V_{DDO} + 0.5V

Package Thermal Impedance, θ_{JA} 47.9°C/W (0 Ifpm)

Storage Temperature, T_{STG} -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

 $\textbf{TABLE 4A. Power Supply DC Characteristics,} \ \ V_{DD} = V_{DDA} = 3.3V \pm 5\%, \ V_{DDOX} = 3.3V \pm 5\% \ \text{or} \ 2.5V \pm 5\%, \ T_{A} = -40^{\circ}\text{C} \ \text{to} \ 85^{\circ}\text{C}$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{DD}	Core Supply Voltage		3.135	3.3	3.465	V
V _{DDA}	Analog Supply Voltage		3.135	3.3	3.465	V
V _{DDOX}	Output Supply Voltage		3.135	3.3	3.465	V
I _{DD}	Power Supply Current				185	mA
I _{DDA}	Analog Supply Current				15	mA
I _{DDOA}	Output Supply Current				20	mA
I _{DDOB}	Output Supply Current				20	mA

 V_{DDOX} denotes V_{DDOA} , V_{DDOB} .

Table 4B. LVCMOS/LVTTL DC Characteristics, $V_{DD} = V_{DDA} = 3.3V \pm 5\%$, $V_{DDOX} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $T_{A} = -40^{\circ}\text{C}$ to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V _⊪ Input High Voltage ∫		MR, DIV_ SELx0, DIV_SELx1, FBDIV_SEL0, FBDIV_SEL1, XTAL_SEL, FB_IN, PLL_SEL		2		V _{DD} + 0.3	V
		REF_IN		2		$V_{DD} + 0.3$	V
V _{IL}	Input Low Voltage	MR, DIV_ SELx0, DIV_SELx1, FBDIV_SEL0, FBDIV_SEL1, XTAL_SEL, FB_IN, PLL_SEL		-0.3		0.8	V
	J	REF_IN		-0.3		1.3	V
I _{IH}	Input High Current	DIV_ SELx0, DIV_SELx1, FBDIV_SEL0, FBDIV_SEL1, MR, FB_IN	$V_{DD} = V_{IN} = 3.465V$			150	μΑ
		XTAL_SEL, PLL_SEL	$V_{DD} = V_{IN} = 3.465V$			5	μΑ
I	Input Low Current	DIV_ SELx0, DIV_SELx1, FBDIV_SEL0, FBDIV_SEL1, MR, FB_IN	$V_{DD} = 3.465V,$ $V_{IN} = 0V$	-5			μΑ
'IL		XTAL_SEL, PLL_SEL	$V_{DD} = 3.465V,$ $V_{IN} = 0V$	-150			μΑ
	Output High V	/oltogo: NOTE 1	$V_{DD} = V_{IN} = 3.465V$	2.6			V
V _{OH}	Output High Voltage; NOTE 1		$V_{DD} = V_{IN} = 2.625V$	1.8			V
V _{OL}	Output Low Vo	oltage; NOTE 1				0.5	V

NOTE 1: Outputs terminated with 50 Ω to V_{DDOX}/2. See Parameter Measurement Information section, "3.3V Output Load Test Circuit".



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TABLE 5. CRYSTAL CHARACTERISTICS

Parameter	Test Conditions	Minimum	Typical	Maximum	Units	
Mode of Oscillation			Fundamental			
Frequency		10		38	MHz	
Equivalent Series Resistance (ESR)				50	Ω	
Shunt Capacitance			7		pF	
Drive Level				1	mW	

Table 6. PLL Input Reference Characteristics, $V_{DD} = V_{DDA} = V_{DDOX} = 3.3V \pm 5\%$, Ta = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f _{REF}	Reference Frequency		8.33		41.67	MHz

Table 7A. AC Characteristics, $V_{DD} = V_{DDA} = V_{DDOX} = 3.3V \pm 5\%$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency				166.67	MHz
t(Ø)	Static Phase Offset; NOTE 1	FREF = 25MHz	0	160	325	ps
tsk(b)	Bank Skew; NOTE 2, 6				60	ps
tsk(o)	Output Skew; NOTE 3, 6				250	ps
tjit(cc)	Cycle-to-Cycle Jitter; 6				120	ps
tjit(per)	Period Jitter, RMS; NOTE 4, 6, 7				20	ps
tsl(o)	Slew Rate		1		4	v/ns
t_	PLL Lock Time				10	ms
t _R /t _F	Output Rise/Fall Time	20% to 80%	200		700	ps
odc	Output Duty Cycle; NOTE 5		48		52	%

All parameters measured with feedback and output dividers set to DIV by 12 unless otherwise noted.

NOTE 1: Defined as the time difference between the input reference clock and the average feedback input signal when the PLL is locked and the input reference frequency is stable. Measured at $V_{\tiny DD}/2$.

NOTE 2: Defined as skew within a bank of outputs at the same voltages and with equal load conditions.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at V_{DDOX}/2.

NOTE 4: Jitter performance using LVCMOS inputs.

NOTE 5: Measured using REF_IN. For XTAL input, refer to Application Note.

NOTE 6: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 7: This parameter is defined as an RMS value.



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Table 7B. AC Characteristics, $V_{DD} = V_{DDA} = 3.3V \pm 5\%$, $V_{DDOX} = 2.5V \pm 5\%$, Ta = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency				166.67	MHz
t(Ø)	Static Phase Offset; NOTE 1	FREF = 25MHz	-365	-105	160	ps
tsk(b)	Bank Skew; NOTE 2, 6				60	ps
tsk(o)	Output Skew; NOTE 3, 6				250	ps
tjit(cc)	Cycle-to-Cycle Jitter; 6				170	ps
tjit(per)	Period Jitter, RMS; NOTE 4, 6, 7				20	ps
tsl(o)	Slew Rate		1		4	v/ns
t_	PLL Lock Time				10	ms
t _R /t _F	Output Rise/Fall Time	20% to 80%	200		700	ps
odc	Output Duty Cycle; NOTE 5		48		52	%

All parameters measured with feedback and output dividers set to DIV by 12 unless otherwise noted.

NOTE 1: Defined as the time difference between the input reference clock and the average feedback input signal when the PLL is locked and the input reference frequency is stable. Measured at $V_{DD}/2$.

NOTE 2: Defined as skew within a bank of outputs at the same voltages and with equal load conditions.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at V_{DDOX}/2.

NOTE 4: Jitter performance using LVCMOS inputs.

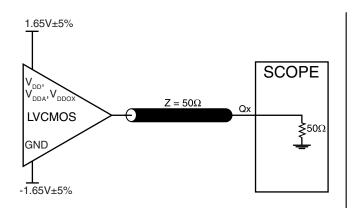
NOTE 5: Measured using REF_IN. For XTAL input, refer to Application Note.

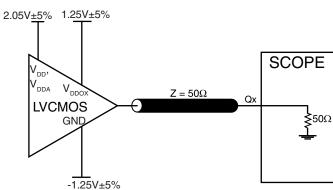
NOTE 6: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 7: This parameter is defined as an RMS value.



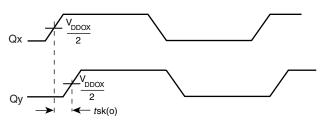
PARAMETER MEASUREMENT INFORMATION

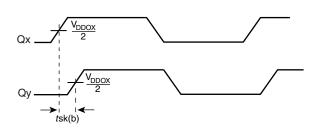




3.3V OUTPUT LOAD AC TEST CIRCUIT (Where X denotes outputs in the same Bank)

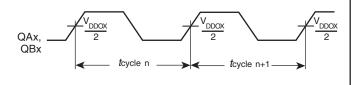
3.3V/2.5V OUTPUT LOAD AC TEST CIRCUIT

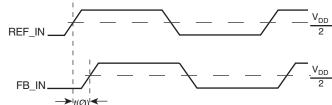




OUTPUT SKEW

BANK SKEW

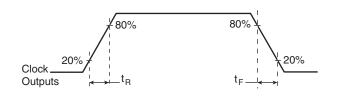


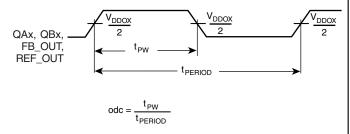


*t*jit(cc) = *t*cycle n −*t*cycle n+1 1000 Cycles

STATIC PHASE OFFSET

CYCLE-TO-CYCLE JITTER





OUTPUT RISE/FALL TIME

OUTPUT PULSE WIDTH/PULSE WIDTH PERIOD

Low Voltage/Low Skew, 1:8 PCI/PCI-X Zero Delay Clock Generator

APPLICATION INFORMATION

Power Supply Filtering Techniques

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. The ICS87608I provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. $V_{\rm DD}, V_{\rm DDA},$ and $V_{\rm DDOX}$ should be individually connected to the power supply plane through vias, and bypass capacitors should be used for each pin. To achieve optimum jitter performance, power supply isolation is required. Figure 1 illustrates how a 10Ω resistor along with a $10\mu F$ and a $.01\mu F$ bypass capacitor should be connected to each $V_{\rm DDA}$.

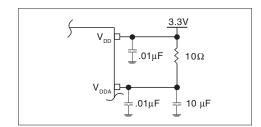


FIGURE 1. POWER SUPPLY FILTERING

RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

INPUTS: OUTPUTS:

LVCMOS CONTROL PINS:

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A $1k\Omega$ resistor can be used.

LVCMOS OUTPUT:

All unused LVCMOS output can be left floating. We recommend that there is no trace attached.

CRYSTAL INPUT INTERFACE

The ICS87608I has been characterized with 18pF parallel resonant crystals. The capacitor values, C1 and C2, shown in *Figure 2* below were determined using a 25MHz, 18pF parallel

resonant crystal and were chosen to minimize the frequency ppm error. The optimum C1 and C2 values can be slightly adjusted for optimum frequency accuracy.

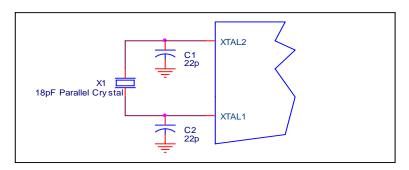


Figure 2. Crystal Input Interface

LVCMOS TO XTAL INTERFACE

The XTAL_IN input can accept a single-ended LVCMOS signal through an AC coupling capacitor. A general interface diagram is shown in *Figure 3*. The XTAL_OUT pin can be left floating. The input edge rate can be as slow as 10ns. For LVCMOS inputs, it is recommended that the amplitude be reduced from full swing to half swing in order to prevent signal interference with the power rail and to reduce noise. This configuration requires that the output impedance of the driver (Ro) plus the

series resistance (Rs) equals the transmission line impedance. In addition, matched termination at the crystal input will attenuate the signal in half. This can be done in one of two ways. First, R1 and R2 in parallel should equal the transmission line impedance. For most 50Ω applications, R1 and R2 can be 100Ω . This can also be accomplished by removing R1 and making R2 50Ω .

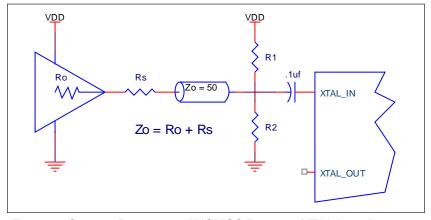


FIGURE 3. GENERAL DIAGRAM FOR LVCMOS DRIVER TO XTAL INPUT INTERFACE

Low Voltage/Low Skew, 1:8 PCI/PCI-X Zero Delay Clock Generator

RELIABILITY INFORMATION

Table 8. $\theta_{\rm JA}{\rm vs.}$ Air Flow Table for 32 Lead LQFP

θ_{A} by Velocity (Linear Feet per Minute)

 0
 200
 500

 Single-Layer PCB, JEDEC Standard Test Boards
 67.8°C/W
 55.9°C/W
 50.1°C/W

 Multi-Layer PCB, JEDEC Standard Test Boards
 47.9°C/W
 42.1°C/W
 39.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for ICS87608I is: 5495





PACKAGE OUTLINE - Y SUFFIX FOR 32 LEAD LQFP

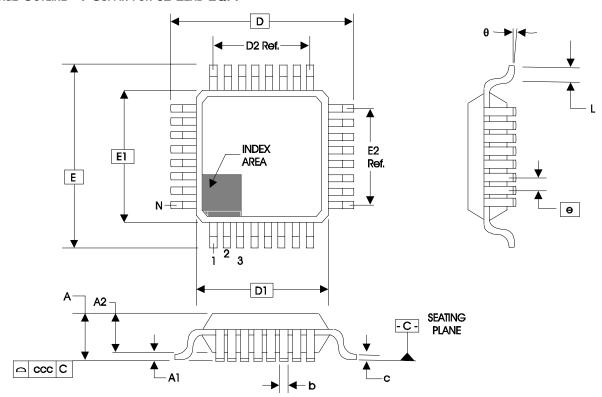


TABLE 9. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS							
	ВВА						
SYMBOL	МІМІМИМ	NOMINAL	MAXIMUM				
N	32						
Α		1.60					
A1	0.05		0.15				
A2	1.35	1.40	1.45				
b	0.30	0.37	0.45				
С	0.09		0.20				
D	9.00 BASIC						
D1	7.00 BASIC						
D2	5.60 Ref.						
E	9.00 BASIC						
E1	7.00 BASIC						
E2	5.60 Ref.						
е	0.80 BASIC						
L	0.45	0.60	0.75				
θ	0°		7°				
ccc			0.10				

Reference Document: JEDEC Publication 95, MS-026



Low Voltage/Low Skew, 1:8 PCI/PCI-X Zero Delay Clock Generator

TABLE 10. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
87608AYI	ICS87608AYI	32 Lead LQFP	tray	-40°C to 85°C
87608AYIT	ICS87608AYI	32 Lead LQFP	1000 tape & reel	-40°C to 85°C
87608AYILF	ICS87608AILF	32 Lead Lead-Free LQFP	tray	-40°C to 85°C
87608AYILFT	ICS87608AILF	32 Lead Lead-Free LQFP	1000 tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS complaint.

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	REVISION HISTORY SHEET					
Rev	Table	Page	Description of Change			
Α		2	Corrected MR in the Block Diagram.	4/6/04		
Α		7	Parameter Measurement Information - for 3.3V Outpt Load AC Test Circuit diagram corrected GND from "-1.165V±5%" to "-1.65V±5%".			
Α	T10	11	Ordering Information Table - added Lead-Free part number.	10/11/04		
В	T7B	6	AC Characteristics Table - changed tjit(cc) from 120ps max to 170ps max.	1/28/05		
В		1	Feature section, Cycle-to-Cycle Jitter note - added "@ 3.3V".	3/11/05		
	T2	3	Pin Characteristics Table - corrected R $_{\text{PULLUP/DOWN}}$ values from 51 Ω max. to 51k Ω typical.			
С	T5	6	Crystal Characterisitics Table - Added Drive Level parameter.	11/11/05		
		9	Added Recommendations for Unused Input and Output Pins.			
	T10	12	Ordering Information Table - added lead-free note.			
C		10	Added LVCMOS to XTAL Interface.	4/28/06		
	T10	12	Ordering Information Table - corrected lead-free marking.	4/20/00		
С	T10	13 15	Updated datasheet's header/footer with IDT from ICS. Removed ICS prefix from Part/Order Number column. Added Contact Page.			



Low Voltage/Low Skew, 1:8 PCI/PCI-X Zero Delay Clock Generator

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